



APPLICATIONS

- Battery-powered devices
- High-efficiency SMPS
- Embedded computing
- Input filters

FEATURES

- Size 4.9mmx4.9mmx4mm
- Semi-Shielded Construction
- Low DCR
- Low Stray Field
- Max Operating Temp +125°C
- RoHS/REACH-Compliant, Halogen-Free

ELECTRICAL CHARACTERISTICS

Parameter			Value	Unit
Inductance ⁽¹⁾	L	±20%	10	μH
Resistance	R_{DC}	typ	56	mΩ
Resistance _{MAX}	$R_{DC\ MAX}$	max	64	mΩ
Rated Current ⁽²⁾	I_R	typ	3.2	A
Saturation Current _{25°C} ⁽³⁾	$I_{SAT\ 25°C}$	typ	3.6	A
Saturation Current _{100°C} ⁽⁴⁾	$I_{SAT\ 100°C}$	typ	3	A
Resonance Frequency	f_r	typ	22	MHz

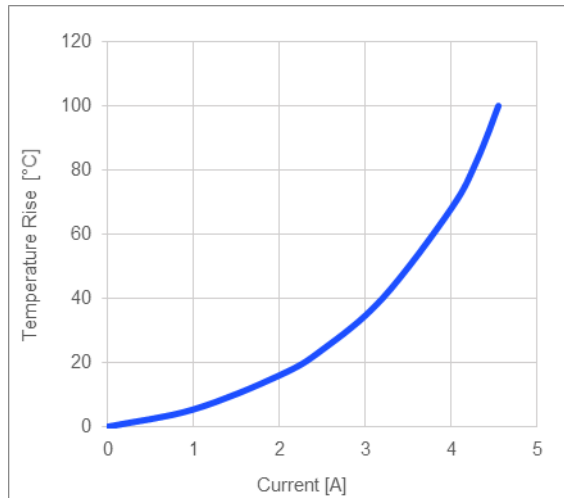
GENERAL SPECIFICATIONS

⁽¹⁾ Inductance	Measured at 100kHz, 100mA
⁽²⁾ Rated Current	Rated current will cause the coil temperature rise ΔT of 40K I_R measured with the inductor soldered in a single-layer PCB. Copper layer thickness 35μm Cu / PCB size 30x50mm. Temperature behavior dependent on circuit design, PCB layout, proximity to other components, and trace dimensions and thickness.
⁽³⁾ Saturation Current _{25°C}	Saturation current will cause L to drop from 30% at 25°C ambient temperature
⁽⁴⁾ Saturation Current _{100°C}	Saturation current will cause L to drop from 30% at 100°C ambient temperature
Temperature Test Condition	Electrical specifications measured at 25°C, 35% RH if not given differently
Operating Condition	Operating temperature: -40°C to +125°C (including temp rise) Should not exceed +125°C under worst-case operation conditions
Storage Condition	Tape and Reel packaging: -10°C to +40°C Humidity: <50% RH

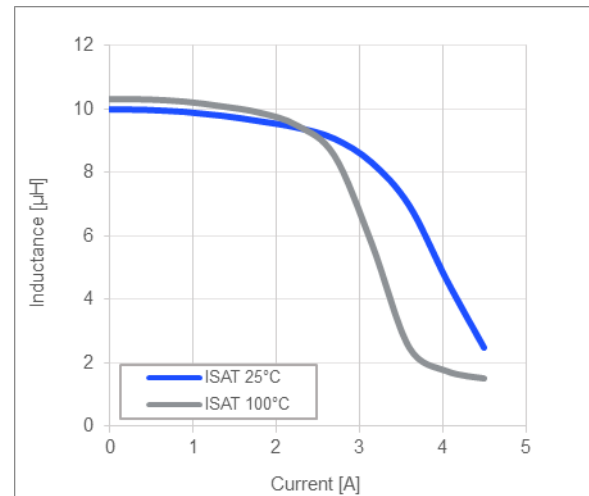
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TYPICAL PERFORMANCE CURVES

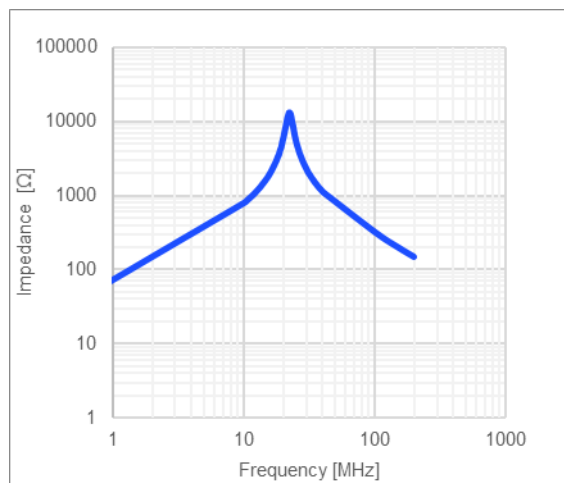
Temperature Rise vs. Current



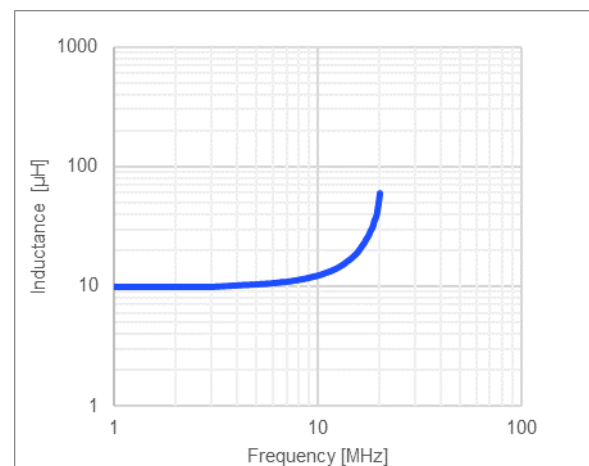
Inductance vs. Current



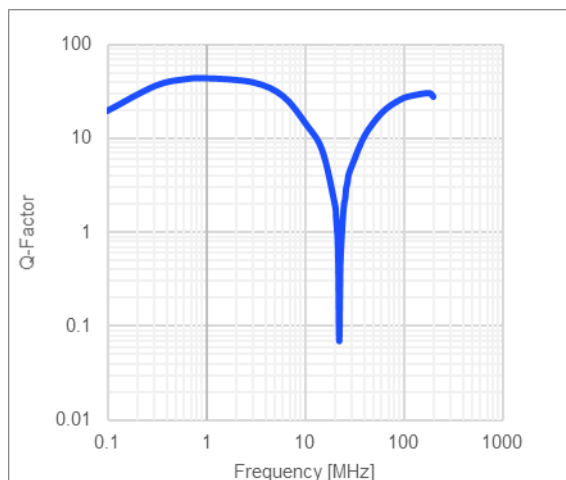
Impedance vs. Frequency



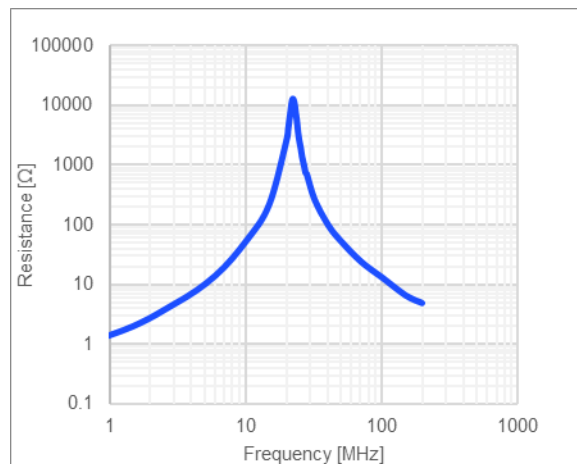
Inductance vs. Frequency



Quality Factor vs. Frequency



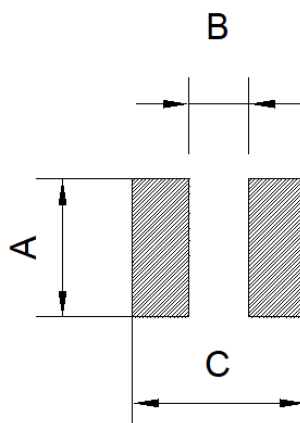
AC Resistance vs. Frequency



LAND PATTERN

Dimensions

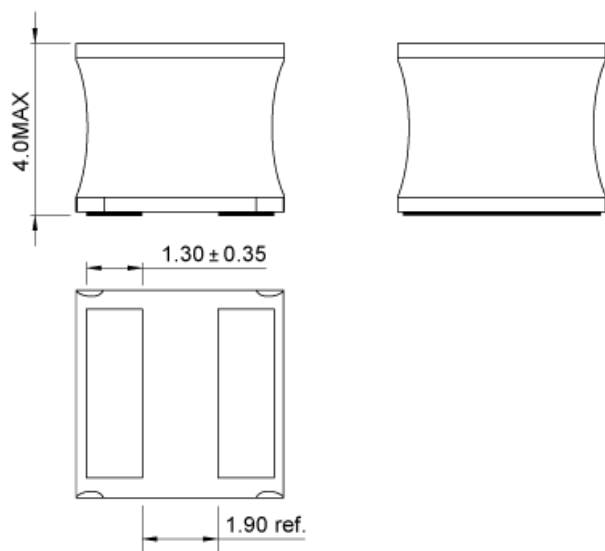
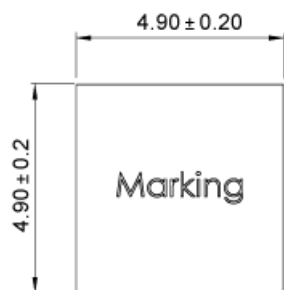
A	4.0 ref.
B	2.10 ref.
C	5.10 ref. (unit in mm)



PRODUCT PACKAGE AND DIMENSIONS

Dimensions

(unit in mm)



TOP MARKING

Marking

Inductance Code 100

ORDERING INFORMATION

Part Number	$L^{(1)}$ typ (μH)	R_{DC} typ (mΩ)	$I_R^{(2)}$ typ (A)	$I_{SAT\ 25^{\circ}C}^{(3)}$ typ (A)	$I_{SAT\ 100^{\circ}C}^{(4)}$ typ (A)
MPL-SE5040-R47	0.47	7.3	8.0	16	13.5
MPL-SE5040-1R0	1.0	9.4	7.6	10.5	9
MPL-SE5040-1R5	1.5	14	6.2	9.3	8.4
MPL-SE5040-2R2	2.2	16	5.4	7.9	7.3
MPL-SE5040-3R3	3.3	22	5.2	6.4	5.2
MPL-SE5040-4R7	4.7	33	4.3	5	4.6
MPL-SE5040-6R8	6.8	45	3.5	4.6	4
MPL-SE5040-100	10	56	3.2	3.6	3
MPL-SE5040-150	15	83	2.5	2.9	2.6
MPL-SE5040-220	22	124	2.1	2.4	2.15

GENERAL SPECIFICATIONS

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(3) Saturation Current $_{25^{\circ}C}$	Saturation current will cause L to drop from 30% at 25°C ambient temperature
(4) Saturation Current $_{100^{\circ}C}$	Saturation current will cause L to drop from 30% at 100°C ambient temperature
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Storage Condition	Tape and Reel packaging: -10°C to +40°C Humidity: <50% RH

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